

Special Issue

Future Additive Manufacturing of Biodegradable Materials, Functionally Graded Materials and Hybrid Biomaterials

Message from the Guest Editor

Additive manufacturing technology has revolutionized the production of parts for many industries. This Special Issue of *Applied Sciences* is dedicated to recent research in this research field. Contributions focused on advanced manufacturing processes on any of the following topics are of particular interest: - Biodegradable materials - Functionally graded materials - Hybrid biomaterials - Simulation of AM process - Material development - AM process characterization, monitoring, and control - Design for additive manufacturing - Innovative processes and applications Papers on numerical simulation, experimental work, or a combination of both are also welcome. Please see the [Special Issue Website](#).

Guest Editor

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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